

FDS9945

60V N-Channel PowerTrench® MOSFET

General Description

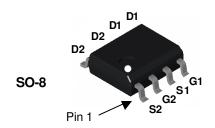
These N Channel Logic Level MOSFET have been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

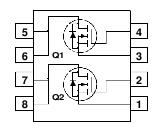
The MOSFET feature faster switching and lower gate charge than other MOSFET with comparable RDS(on) specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 3.5 A, 60 V. $R_{DS(ON)} = 0.100\Omega$ @ $V_{GS} = 10$ V $R_{DS(ON)} = 0.200\Omega$ @ $V_{GS} = 4.5$ V
- Optimized for use in switching DC/DC converters with PWM controllers
- · Very fast switching
- Low gate charge.





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		±20	V
l _D	Drain Current - Continuous	(Note 1a)	3.5	А
	- Pulsed		10	
P _D	Power Dissipation for Single Operation	(Note 1a)	2	W
		(Note 1b)	1.6	
		(Note 1c)	1.0	
T _J , T _{STG}	Operating and Storage Junction Temperat	ure Range	-55 to +175	°C

Thermal Characteristics

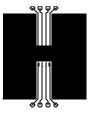
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78 (steady state), 50 (10 sec)	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	135	°C/W
ReJC	Thermal Resistance, Junction-to-Case	(Note 1)	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS9945	FDS9945	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics			I	ı	ı
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		62.5		mV/°C
loss	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
l _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	V _{GS} = -20 V V _{DS} = 0 V			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2.5	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-6		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$\begin{array}{cccccccccccccccccccccccccccccccccccc$		74 103 126	100 200 170	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, = V_{DS} = 30 \text{ V}$	10			Α
g rs	Forward Transconductance	$V_{DS} = 5V$, $I_{D} = 3.5 A$		8.6		S
Dynamic	Characteristics		•	•		
C _{iss}	Input Capacitance	$V_{DS} = 30 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		420		pF
Coss	Output Capacitance	f = 1.0 MHz		48		pF
C _{rss}	Reverse Transfer Capacitance			20		pF
Switchin	g Characteristics (Note 2)		•			
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, \qquad I_{D} = 1 \text{ A},$		7	14	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		4.3	8.6	ns
t _{d(off)}	Turn-Off Delay Time			19	34	ns
t _f	Turn-Off Fall Time			3	6	ns
Qg	Total Gate Charge	$V_{DS} = 30 \text{ V}, \qquad I_{D} = 3.5 \text{ A},$		8	13	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 5 V$		4		nC
Q _{gd}	Gate-Drain Charge			2.5		nC
Drain-So	ource Diode Characteristics	and Maximum Ratings	•		•	•
ls	Maximum Continuous Drain-Source				2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.1 \text{ A}$ (Note 2)		0.8	1.2	٧

1. R_{NA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 78°/W when mounted on a 0.5irf² pad of 2 oz copper



b) 125°/W when mounted on a 0.02 in pad of 2 oz copper



c) 135°/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width $< 300 \mu s$, Duty Cycle < 2.0%

Typical Characteristics

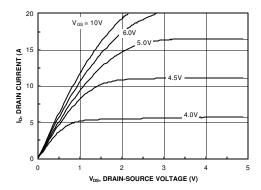


Figure 1. On-Region Characteristics.

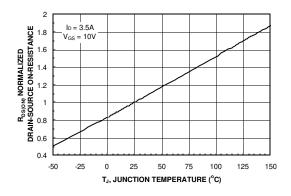


Figure 3. On-Resistance Variation with Temperature.

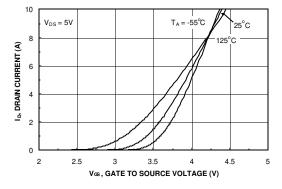


Figure 5. Transfer Characteristics.

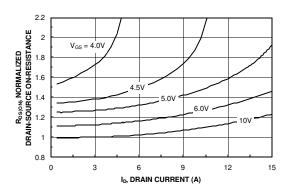


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

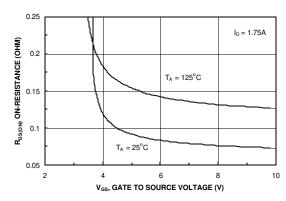


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

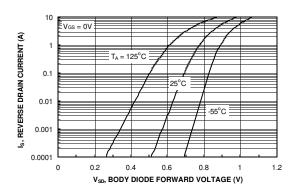
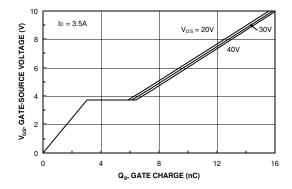


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



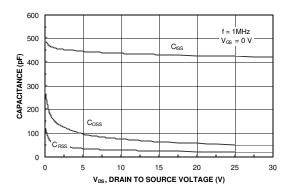
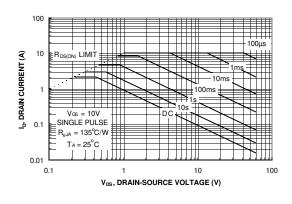


Figure 7. Gate Charge Characteristics.





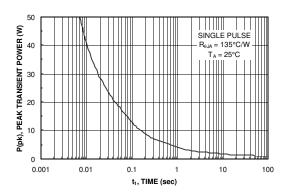


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

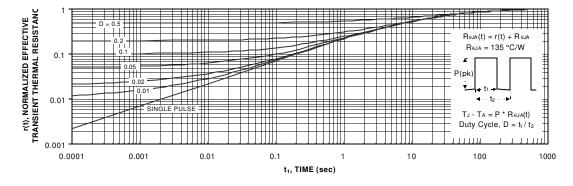


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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General description

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Models

Qualification Support

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Product status/pricing/packaging

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Product	Product status	Pb-free Status	Pricing*	Package type	Leads	Packing method	Package Marking Convention**
FDS9945	Full Production	Full Production	\$0.74	<u>SO-8</u>	8	TAPE REEL	Line 1: \$Y (Fairchild logo) & Z (Asm. Plant Code) & 2 (2-Digit Date Code) & T (Die Trace Code) Line 2: FDS Line 3: 9945

^{*} Fairchild 1,000 piece Budgetary Pricing

** A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a Fairchild distributor to obtain samples



Indicates product with Pb-free second-level interconnect. For more information click here.

Package marking information for product FDS9945 is available. Click here for more information .

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Models

Package & leads	Condition	Temperature range	Software version	Revision date		
PSPICE						
SO-8-8 <u>Electrical</u> 25°C to 125°C Orcad 9.1 Aug 2, 2004						

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Qualification Support

Click on a product for detailed qualification data

Product
FDS9945

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